

Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**
 Contact Info: ti.com/support
 Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**
 Created on: **06/04/2022**

Details for "OMAPL138EZWT3E"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
OMAPL138EZWT3E	SNAGCU	Level-3-260C-168 HR	TI PHILIPPINES A/T	ZWT 361	16x16x0.9	667.9

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Aluminum and Its Alloys	Aluminum	7429-90-5	0.000003	0.000146	1	0	0
Copper and Its Alloys	Copper	7440-50-8	1.933558	94.326206	943262	0.289499	2895
Copper and Its Alloys	Iron	7439-89-6	0.000009	0.000439	4	0.000001	0
Not Categorized	Proprietary Materials		0.000318	0.015513	155	0.000048	0
Other Inorganic Materials	Sulfur	7704-34-9	0.000001	0.000049	0	0	0
Precious Metals	Gold	7440-57-5	0.021715	1.059339	10593	0.003251	33
Precious Metals	Palladium	7440-05-3	0.094224	4.5966	45966	0.014108	141
Precious Metals	Silver	7440-22-4	0.000035	0.001707	17	0.000005	0
Sub-Total			2.049863	100	1000000	0.306913	3069
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	5.862481	82.000001	820000	0.877752	8778
Thermoplastics	Epoxy	85954-11-6	1.286886	17.999999	180000	0.192677	1927
Sub-Total			7.149367	100	1000000	1.070429	10704
Mold Compound							
Other Inorganic Materials	Aluminum Nitride	24304-00-5	1.771613	0.52	5200	0.265252	2653
Other Inorganic Materials	Fused Silica	60676-86-0	306.625266	90	900000	45.909057	459091
Other Nonferrous Metals and Alloys	Metal Oxide	Trade Secret	1.022084	0.3	3000	0.15303	1530
Other Plastics and Rubber	Carbon Black	1333-86-4	0.851737	0.25	2500	0.127525	1275
Other Plastics and Rubber	Organic Phosphorus	1330-78-5	0.681389	0.2	2000	0.10202	1020
Thermoplastics	Epoxy	85954-11-6	29.742651	8.73	87300	4.453179	44532
Sub-Total			340.69474	100	1000000	51.01063	510101
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	22.468654	100	1000000	3.364089	33641
Sub-Total			22.468654	100	1000000	3.364089	33641
Solder Ball							
Copper and Its Alloys	Copper	7440-50-8	0.869172	0.5	5000	0.130136	1301
Nickel and Its Alloys	Nickel	7440-02-0	0.086917	0.05	500	0.013014	130
Other Nonferrous Metals and Alloys	Tin	7440-31-5	170.792343	98.25	982500	25.571654	255717
Precious Metals	Silver	7440-22-4	2.086013	1.2	12000	0.312325	3123
Sub-Total			173.834445	100	1000000	26.027129	260271
Substrate							
Ceramics / Glass	Woven Glass Fiber	65997-17-3	17.83477	14.654694	146547	2.670287	26703
Copper and Its Alloys	Copper	7440-50-8	46.162757	37.931585	379316	6.911657	69117
Nickel and Its Alloys	Nickel	7440-02-0	4.452845	3.658869	36589	0.666696	6667
Other Inorganic Materials	Silica	7631-86-9	19.398858	15.939893	159399	2.904468	29045
Other Nonferrous Metals and Alloys	Barium Sulfate	7727-43-7	1.564125	1.28523	12852	0.234187	2342
Precious Metals	Gold	7440-57-5	0.578854	0.47564	4756	0.086668	867
Thermoplastics	Epoxy	85954-11-6	31.70784	26.05409	260541	4.747414	47474
Sub-Total			121.700049	100	1000000	18.221377	182214
Total			667.897118			100	1000000

Important Note
 The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

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Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.